

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (original): A semiconductor wafer cleaning system, comprising:

a cleaning chamber;

a wafer support disposed within said chamber and configured to support a plurality of wafers within said chamber as spaced from one another in a first direction;

a source of cleaning solution associated with said cleaning chamber such that said cleaning chamber can be filled with cleaning solution from said source;

a source of de-ionized water;

de-ionized water supply nozzles connected to said source of de-ionized water and oriented to spray deionized water from said source thereof into said chamber towards wafers supported by said wafer support,

each of the de-ionized water supply nozzles having a main body in the form of a pipe defining an inner nozzle passageway, and a plurality of sets of nozzle holes connected to the inner nozzle passageway, the main bodies of said de-ionized water supply nozzles extending longitudinally in said first direction at opposites sides of said wafer support, the nozzle holes of each said set lying in a plane perpendicular to said first direction, and said sets of nozzle holes being spaced from each other along the length of the main body, and

each said set of said nozzle holes subtending an angle of 80~100° about the inner nozzle passageway from which the set of nozzle holes extends so that the de-ionized water is sprayed through each said set of nozzle holes over a range of 80~100° as measured in the circumferential direction of the main body